TOSHIBA Bi-CMOS Integrated Circuit Silicon Monolithic

TB62777FNG, TB62777FG

8-Channel Constant-Current LED Driver of the 3.3-V and 5-V Power Supply Voltage Operation

The TB62777FNG/FG is comprised of constant-current drivers designed for LEDs and LED panel displays.

The regulated current sources are designed to provide a constant current, which is adjustable through one external resistor.

The TB62777FNG/FG incorporates eight channels of shift registers, latches, AND gates and constant-current outputs.

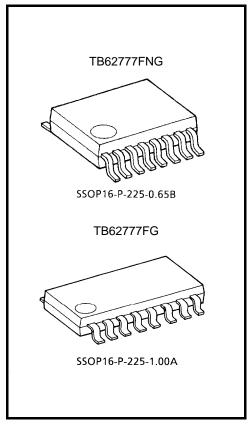
Fabricated using the Bi-CMOS process, the TB62777FNG/FG is capable of high-speed data transfers.

The TB62777FNG/FG is RoHS.

Features

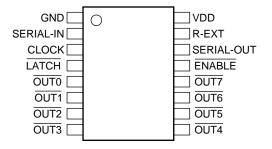
- Power supply voltages: V_{DD} = 3.3 V/5 V
- Output drive capability and output count: 50 mA × 8 channels
- Constant-current output range: 5 to 40 mA
- Voltage applied to constant-current output terminals: 0.4 V (min, IOUT = 5 to 40 mA)
- Designed for common-anode LEDs
- Thermal shutdown (TSD) (min: 150°C)
- Power on reset (POR)
- Logical input signal voltage level: 3.3-V and 5-V CMOS interfaces (Schmitt trigger input)
- Maximum output voltage: 25V
- Serial data transfer rate: 25 MHz (max) @cascade connection
- Operating temperature range: $T_{opr} = -40$ to 85°C
- Package: SSOP16-P-225-0.65B/ SSOP16-P-225-1.00A
- Constant-current accuracy

Output Voltage	Current accuracy Between Channels	Current Accuracy Between ICs	Output Current
0.4 V to 4 V	±3%	±6%	15 mA

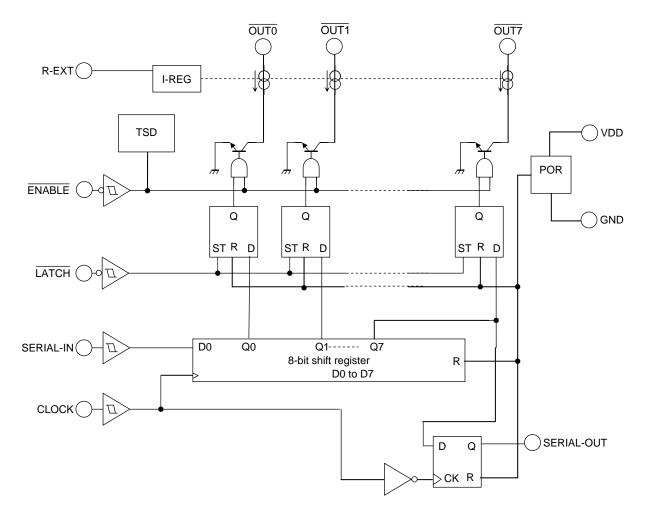


Weight: SSOP16-P-225-0.65B 0.07 g (typ.) SSOP16-P-225-1.00A 0.14 g (typ.)

Pin Assignment (top view)



Block Diagram



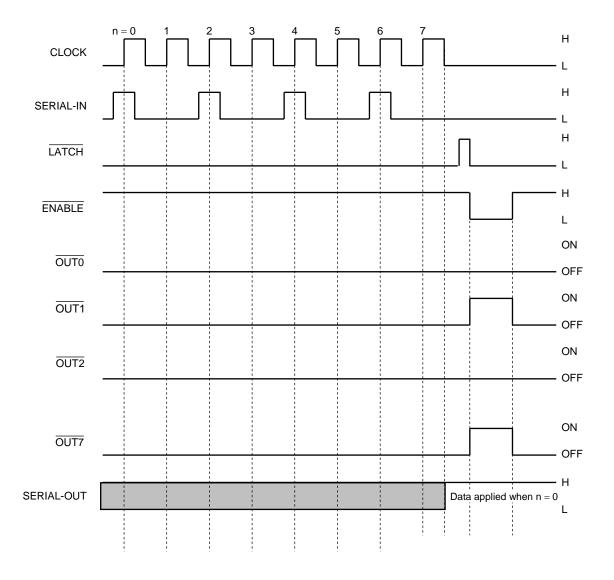
Truth Table

CLOCK	LATCH	ENABLE	SERIAL-IN	OUTO OUT5 OUT7	SERIAL-OUT
\int	Н	L	Dn	Dn Dn – 5 Dn – 7	No change
	L	L	Dn + 1	No Change	No change
	Н	L	Dn + 2	Dn + 2 Dn – 3 Dn – 5	No change
	Х	Н	Dn + 3	OFF	No change
$\overline{\downarrow}$	X	Н	Dn + 3	OFF	Dn −4

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Note 1: $\overline{OUT0}$ to $\overline{OUT7}$ = On when Dn = H; $\overline{OUT0}$ to $\overline{OUT7}$ = Off when Dn = L.

Timing Diagram



Note 1: Latches are level-sensitive, not edge-triggered.

Note 2: The TB62777FNG can be used at 3.3 V or 5.0 V. However, the V_{DD} supply voltage must be equal to the input voltage.

Note 3: Serial data is shifted out of SERIAL-OUT on the falling edge of CLOCK.

Marks: The latches hold data while the LATCH terminal is held Low. When the LATCH terminal is High, the latches do not hold data and pass it transparently. When the ENABLE terminal is Low, OUTO to OUT7 toggle between ON and OFF according to the data. When the ENABLE terminal is High, OUTO to OUT7 are forced OFF.

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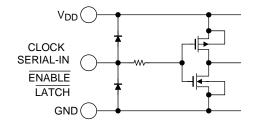
Terminal Description

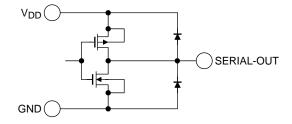
Pin No.	Pin Name	Function
1	GND	GND terminal
2	SERIAL-IN	Serial data input terminal
3	CLOCK	Serial clock input terminal
4	LATCH	Latch input terminal
5	OUT0	Constant-current output terminal (Open collector)
6	OUT1	Constant-current output terminal (Open collector)
7	OUT2	Constant-current output terminal (Open collector)
8	OUT3	Constant-current output terminal (Open collector)
9	OUT4	Constant-current output terminal (Open collector)
10	OUT5	Constant-current output terminal (Open collector)
11	OUT6	Constant-current output terminal (Open collector)
12	OUT7	Constant-current output terminal (Open collector)
13	ENABLE	Output enable input terminal All outputs (OUTO to OUT7) are disabled when the ENABLE terminal is driven High, and enabled when it is driven Low.
14	SERIAL-OUT	Serial data output terminal. Serial data is clocked out on the falling edge of CLOCK.
15	R-EXT	An external resistor is connected between this terminal and ground. OUT0 to OUT7 are adjusted to the same current value.
16	V_{DD}	Power supply terminal

Equivalent Circuits for Inputs and Outputs

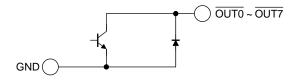
CLOCK, SERIAL-IN, ENABLE, LATCH Terminals

SERIAL-OUT Terminal





OUT0 to OUT7 Constant-current Output Terminals



Absolute Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating	Unit
Supply voltage	V_{DD}	6.0	V
Input voltage	V _{IN}	-0.3 to V _{DD} + 0.3 (Note 1)	V
Output current	lout	55	mA/ch
Output voltage	Vout	-0.3 to 25	V
Power dissipation	P _d	1.19(FG TYPE) / 1.02(FNG TYPE) (Notes 2 and 3)	W
Thermal resistance	R _{th (j-a)}	105(FG TYPE) / 122(FNG TYPE) (Note 2)	°C/W
Operating temperature range	T _{opr}	-40 to 85	°C
Storage temperature range	T _{stg}	-55 to 150	°C
Maximum junction temperature	Tj	150	°C

Note 1: However, do not exceed 6.0 V.

Note 2: When mounted on a PCB ($76.2 \times 114.3 \times 1.6$ mm; Cu = 30%; 35- μ m-thick; SEMI-compliant)

Note 3: Power dissipation is reduced by 1/R_{th (j-a)} for each °C above 25°C ambient.

Operating Ranges (unless otherwise specified, $Ta = -40^{\circ}C$ to 85°C)

Characteristics	Symbol	Test Cond	lition	Min	Тур.	Max	Unit
Supply voltage	V_{DD}	_		3	_	5.5	V
Output voltage	Vout	OUT0 to OUT7		0.4	_	4	V
	lout	OUT0 to OUT7		5	_	40	mA/ch
Output current	Іон	SERIAL-OUT		_	_	-5	- mA
	l _{OL}	SERIAL-OUT		_	_	5	mA
	V _{IH}	SERIAL-IN/CLOCK/		0.7 × V _{DD}	_	V _{DD}	- V
Input voltage	V _{IL}	LATCH / ENABLE		GND	_	0.3 × V _{DD}	
Clock frequency	f _{CLK}	Cascade connection		_	_	25	MHz
LATCH pulse width	t _{wLAT}		(Note 2)	20	_	_	no
CLOCK pulse width	t _{wCLK}		(Note 2)	20	_	_	ns
ENABLE 1 :W	+	$I_{OUT} \ge 20 \text{ mA}$	(Note 2)	2	_	_	μS
ENABLE pulse width	t _{wENA}	$5 \text{ mA} \le I_{OUT} \le 20 \text{ mA}$	(Note 2)	3	_	_	
Setup time	tSETUP1			5	_	_	
Setup time	tSETUP2		(Note 2)	5	_	_	no
	tHOLD1		(Note 2)	5	_	_	ns
Hold time	t _{HOLD2}			5	_	_	
Maximum clock rise time	t _r	Single operation	(Notes 1 and 2)	_	_	5	
Maximum clock fall time	t _f	Single operation	(INULES I AIIU Z)			5	μS

Note 1: For cascade operation, the CLOCK waveform might become ambiguous, causing the t_r and t_f values to be large. Then it may not be possible to meet the timing requirement for data transfer. Please consider the timing carefully.

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Note 2: Please see the timing waveform on page 9.

Electrical Characteristics (Unless otherwise specified, Ta = 25°C, $V_{DD} = 4.5$ to 5.5 V)

Characteristics	Symbol	Test Circuit	Test Condition	Min	Тур.	Max	Unit
Output current	l _{OUT1}	5	$V_{OUT} = 0.4 \text{ V}, \text{ R-EXT} = 1.2 \text{ k}\Omega$ $V_{DD} = 5 \text{ V},$	_	15	_	mA
Output current error between ICs	Δl _{OUT1}	5	$V_{OUT} = 0.4 \text{ V, R-EXT} = 1.2 \text{ k}\Omega$ All channels ON $V_{DD} = 5 \text{ V,}$	_	±3	±6	%
Output current error between channels	Δl _{OUT2}	5	$V_{OUT} = 0.4$ V, R-EXT = 1.2 k Ω All channels ON $V_{DD} = 5$ V		±1	±3	%
Output leakage current	loz	5	V _{OUT} = 25 V	_	_	1	μΑ
Input voltage	V_{IH}	_	SERIAL-IN/CLOCK/ LATCH / ENABLE	0.7 × V _{DD}	_	V _{DD}	V
	V_{IL}	_	SERIAL-IN/CLOCK/ LATCH / ENABLE	GND	_	0.3 × V _{DD}	
	I _{IH}	2	V _{IN} = V _{DD} CLOCK/SERIAL-IN / LATCH / ENABLE	_	_	1	μА
Input current	կլ	3	V _{IN} = GND CLOCK/SERIAL-IN/ LATCH / ENABLE			-1	
SERIAL-OUT output voltage	V _{OL}	1	$I_{OL} = 5.0 \text{ mA}, V_{DD} = 5 \text{ V}$	_	_	0.3	V
	V_{OH}	1	$I_{OH} = -5.0 \text{ mA}, V_{DD} = 5 \text{ V}$	4.7	_	_	
Changes in constant output current dependent on V _{DD}	%/V _{DD}	5	V _{DD} = 3 V to 5.5 V	_	1	2	%
	I _{DD} (OFF) 1	4	R-EXT = OPEN, V _{OUT} = 25.0 V	_	_	1	
Supply current	I _{DD} (OFF) 2	4	R-EXT = 1.2 k Ω , V _{OUT} = 25.0 V, All channels OFF			5	mA
	I _{DD} (ON)	4	R-EXT = 1.2 k Ω , V _{OUT} = 0.4 V, All channels ON	_	_	9	

Switching Characteristics (Unless otherwise specified, Ta = 25°C, $V_{DD} = 4.5$ to 5.5V)

Characteristics	Symbol	Test Circuit	Test Condition (Note 1)	Min	Тур.	Max	Unit
	^t pLH1	6	CLK- OUTn , LATCH = "H", ENABLE = "L"	_	20	300	
	^t pLH2	6	LATCH – OUTn , ENABLE = "L"	_	20	300	
	t _{pLH3}	6	ENABLE – OUTn , LATCH = "H"	_	20	300	
Propagation delay time	t _{pLH}	6	CLK-SERIAL OUT	2	10	14	
Propagation delay time	^t pHL1	6	CLK- OUTn , LATCH = "H", ENABLE = "L"	_	30	340	ns
	^t pHL2	6	LATCH – OUTn , ENABLE = "L"	_	70	340	
	t _{pHL3}	6	ENABLE – OUTn , LATCH = "H"	_	70	340	
	t _{pHL}	6	CLK-SERIAL OUT	2	10	14	
Output rise time	t _{or}	6	10% to 90% points of OUT0 to OUT7 voltage waveforms		20	150	
Output fall time	t _{of}	6	90% to 10% points of OUT0 to OUT7 voltage waveforms	_	125.	300	

Note 1: $T_{opr} = 25$ °C, $V_{DD} = V_{IH} = 5$ V, $V_{IL} = 0$ V, $R_{EXT} = 1.2$ k Ω , $I_{OUT} = 15$ mA, $V_L = 5.0$ V, $C_L = 10.5$ pF (see test circuit 6.)

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Electrical Characteristics (Unless otherwise specified, Ta = 25°C, $V_{DD} = 3$ to 3.6 V)

Characteristics	Symbol	Test Circuit	Test Condition	Min	Тур.	Max	Unit
Output current	l _{OUT1}	5	V_{OUT} = 0.4 V, R-EXT = 1.2 k Ω V _{DD} = 3.3 V	_	15	_	mA
Output current error between ICs	Δl _{OUT1}	5	$V_{OUT} = 0.4$ V, R-EXT = 1.2 k Ω All channels ON $V_{DD} = 3.3$ V	_	±3	±6	%
Output current error between channels	Δl _{OUT2}	5	$V_{OUT} = 0.4$ V, R-EXT = 1.2 k Ω All channels ON $V_{DD} = 3.3$ V	_	±1	±3	%
Output leakage current	I _{OZ}	5	V _{OUT} = 25 V	_	_	1	μΑ
Input voltage	V _{IH}	_	SERIAL-IN/CLOCK/ LATCH / ENABLE	0.7 × V _{DD}	_	V _{DD}	V
	V _{IL}	_	SERIAL-IN/CLOCK/ LATCH / ENABLE	GND	_	0.3 × V _{DD}	V
	lіН	2	V _{IN} = VDD CLOCK/SERIAL-IN/ LATCH / ENABLE	_	_	1	- μΑ
Input current	lıL	3	V _{IN} = GND CLOCK/SERIAL-IN/ LATCH / ENABLE	_	_	-1	
SERIAL-OUT output voltage	V _{OL}	1	I_{OL} = 5.0 mA, V_{DD} = 3.3 V	_	_	0.3	V
	V_{OH}	1	$I_{OH} = -5.0 \text{ mA}, V_{DD} = 3.3 \text{ V}$	3.0	_	_	Ţ
Changes in constant output current dependent on V _{DD}	%/V _{DD}	5	V _{DD} = 3 V to 5.5 V	_	1	2	%
	I _{DD} (OFF) 1	4	R-EXT = OPEN, V _{OUT} = 25.0 V	_	_	1	
Supply current	I _{DD} (OFF) 2	4	R-EXT = 1.2 k Ω , V _{OUT} = 25.0 V, All channels OFF			5	mA
	I _{DD (ON)}	4	R-EXT = 1.2 k Ω , V _{OUT} = 0.4 V, All channels ON	_	_	9	

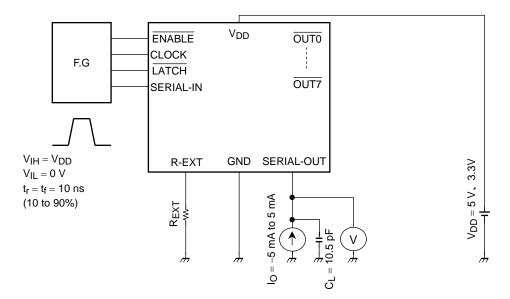
Switching Characteristics (Unless otherwise specified, Ta = 25°C, $V_{DD} = 3$ to 3.6 V)

Characteristics	Symbol	Test Circuit	Test Condition (Note 1)	Min	Тур.	Max	Unit
	^t pLH1	6	CLK- OUTn , LATCH = "H", ENABLE = "L"	_	_	300	
	t _{pLH2}	6	LATCH - OUTn , ENABLE = "L"	_		300	
	t _{pLH3}	6	ENABLE - OUTn , LATCH = "H"	_		300	
Propagation delay time	t _{pLH}	6	CLK-SERIAL OUT	2	_	14	
Propagation delay time	^t pHL1	6	CLK- OUTn , LATCH = "H", ENABLE = "L"	_	_	340	ns
	^t pHL2	6	LATCH - OUTn , ENABLE = "L"	_	_	340	
	t _{pHL3}	6	ENABLE - OUTn , LATCH = "H"	_	_	340	
	t _{pHL}	6	CLK-SERIAL OUT	2	_	14	
Output rise time	t _{or}	6	10% to 90% points of OUT0 to OUT7 voltage waveforms	_	_	150	
Output fall time	t _{of}	6	90% to 10% points of OUT0 to OUT7 voltage waveforms	_	_	300	

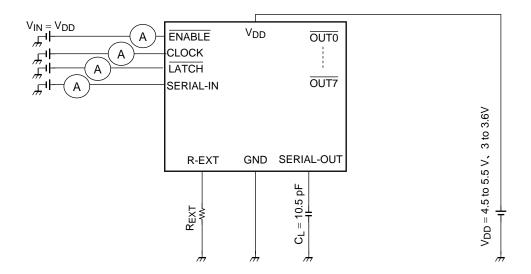
Note 1: $T_{opr} = 25$ °C, $V_{DD} = V_{IH} = 3.3$ V, $V_{IL} = 0$ V, $R_{EXT} = 1.2$ k Ω , $I_{OUT} = 15$ mA, $V_L = 5.0$ V, $C_L = 10.5$ pF (see test circuit 6.)

Test Circuits

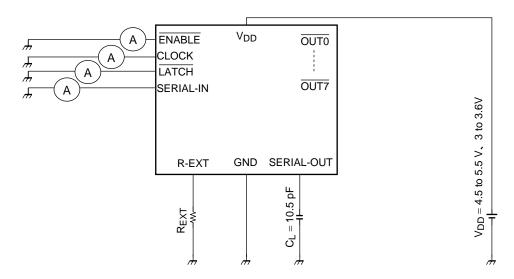
Test Circuit 1: SERIAL-OUT output voltage (V_{OH}/V_{OL})



Test Circuit 2: Input Current (I_{IH})



Test Circuit 3: Input Current (IIL)

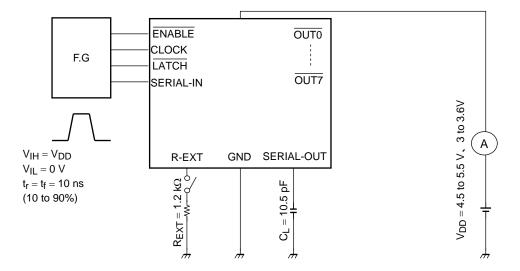


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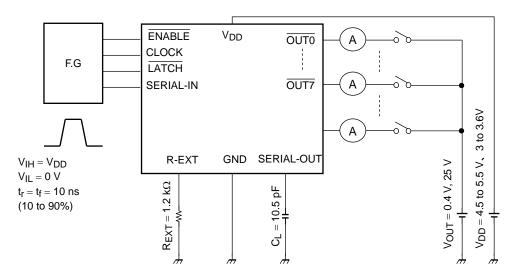


Test Circuit 4: Supply Current



Note: The output terminal is based on the power supply current conditions on page 6 and 7.

Test Circuit 5: Output Current (I_{OUT1}), Output Leakage Current (I_{OZ}), Output Current Error Margin (ΔI_{OUT1}/ΔI_{OUT2}), Current Variation with V_{DD} (%/V_{DD})

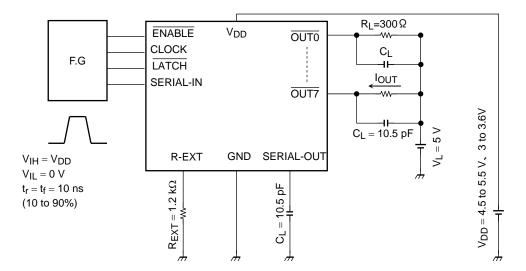


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Theoretical output current = 1.13 $V/R_{EXT} \times 16$

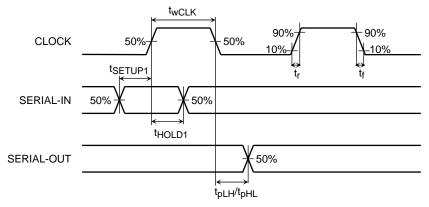


Test Circuit 6: Switching Characteristics

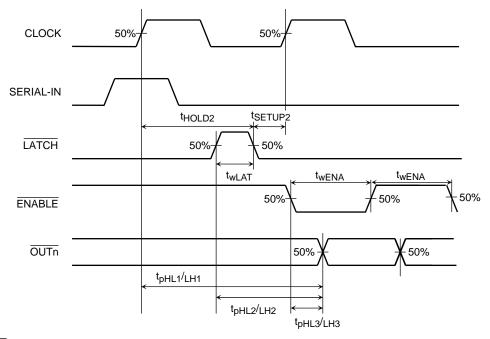


Timing Waveforms

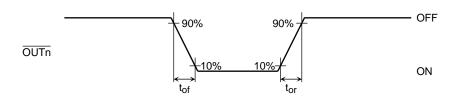
1. CLOCK, SERIAL-IN, SERIAL-OUT



2. CLOCK, SERIAL-IN, LATCH, ENABLE, OUTn



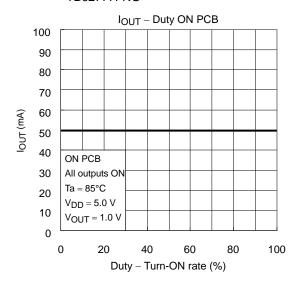
3. OUTn

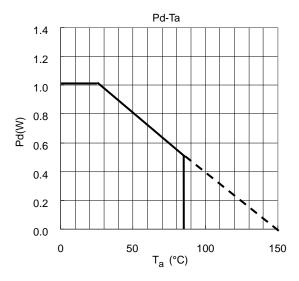


Note: Timing chart waveforms are presented to describe functions and operations and may be simplified. Adequate consideration should be given to timing conditions.

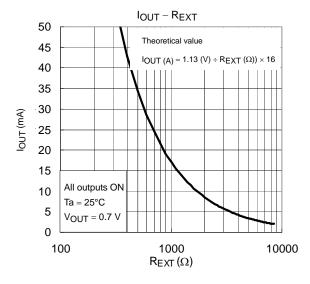
Output Current vs. Derating (lighting rate) Graph

PCB Conditions: $76.2\times114.3\times1.6$ mm, Cu = 30%, 35- μm Thick, SEMI-Compliant TB62777FNG





Output Current vs. External Resistor (typ.)

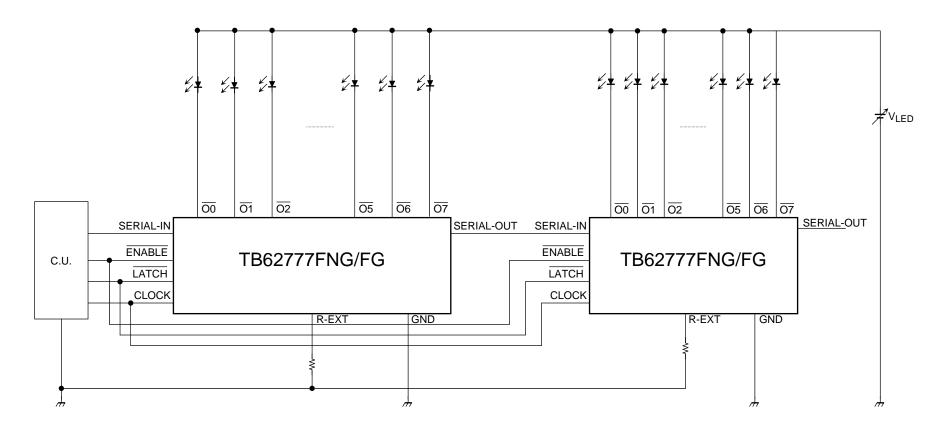


The above graphs are presented merely as a guide and do not constitute any guarantee as to the performance or characteristics of the device. Each product design should be fully evaluated in a real-world environment.

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Application Circuit 1: General Composition for Static Lighting of LEDs

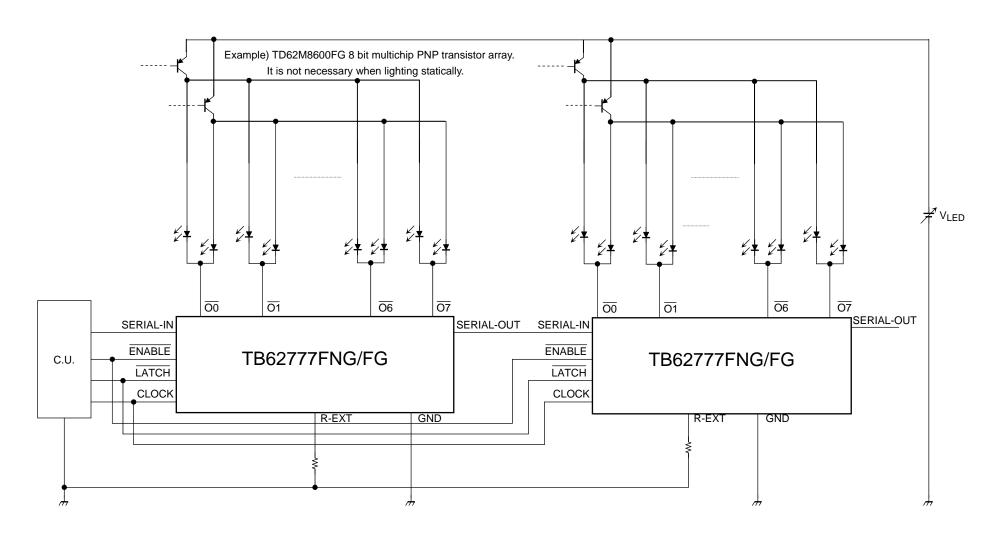
In the following diagram, it is recommended that the LED supply voltage (VLED) be equal to or greater than the sum of V_f (max) of all LEDs plus 0.7 V.



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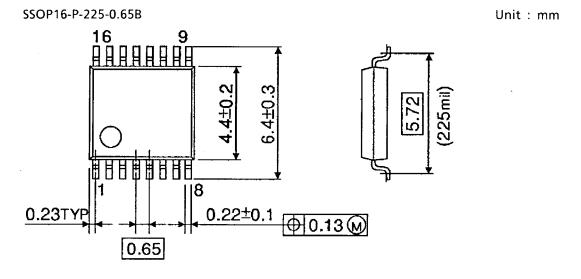
Application Circuit 2: General Composition for Dynamic Lighting of LEDs

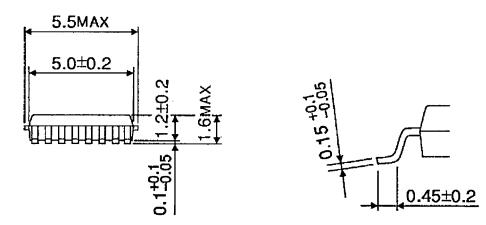
In the following diagram, it is recommended that the LED supply voltage (VLED) be equal to or greater than the sum of V_f (max) of all LEDs plus 0.7 V.



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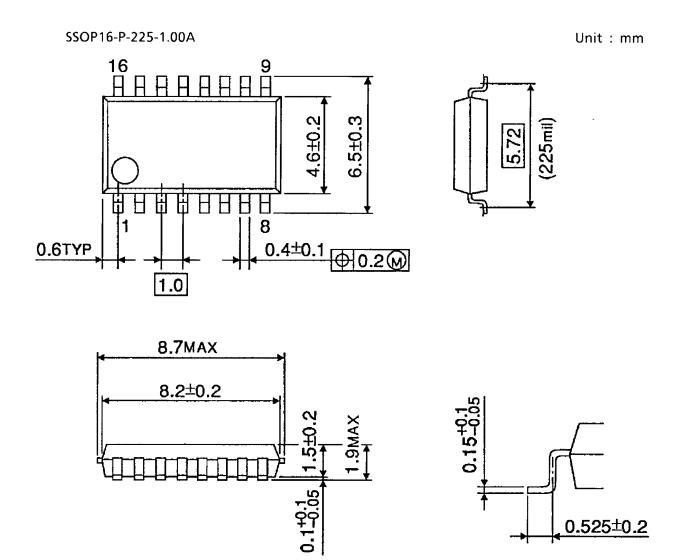
Package Dimensions





Weight: 0.07 g (typ.)

Package Dimensions



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Weight: 0.14 g (typ.)

Notes on Contents

1. Block Diagrams

Some of the functional blocks, circuits, or constants in the block diagram may be omitted or simplified for explanatory purposes.

2. Equivalent Circuits

The equivalent circuit diagrams may be simplified or some parts of them may be omitted for explanatory purposes.

3. Timing Charts

Timing charts may be simplified for explanatory purposes.

4. Application Circuits

The application circuits shown in this document are provided for reference purposes only. Thorough evaluation is required, especially at the mass production design stage.

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5. Test Circuits

Components in the test circuits are used only to obtain and confirm the device characteristics. These components and circuits are not guaranteed to prevent malfunction or failure from occurring in the application equipment.

IC Usage Considerations

Notes on handling of ICs

- (1) The absolute maximum ratings of a semiconductor device are a set of ratings that must not be exceeded, even for a moment. Do not exceed any of these ratings.
 Exceeding the rating(s) may cause breakdown, damage or deterioration of the device, and may result in injury by explosion or combustion.
- (2) Use an appropriate power supply fuse to ensure that a large current does not continuously flow in the event of over current and/or IC failure. The IC will fully break down when used under conditions that exceed its absolute maximum ratings, when the wiring is routed improperly or when an abnormal pulse noise occurs from the wiring or load, causing a large current to continuously flow. Such a breakdown can lead to smoke or ignition. To minimize the effects of a large current flow in the event of breakdown, fuse capacity, fusing time, insertion circuit location, and other such suitable settings are required.
- (3) If your design includes an inductive load such as a motor coil, incorporate a protection circuit into the design to prevent device malfunction or breakdown caused by the current resulting from the inrush current at power ON or the negative current resulting from the back electromotive force at power OFF. IC breakdown may cause injury, smoke or ignition.
 For ICs with built-in protection functions, use a stable power supply with. An unstable power supply may cause the protection function to not operate, causing IC breakdown. IC breakdown may cause injury, smoke or ignition.
- (4) Do not insert devices incorrectly or in the wrong orientation. Make sure that the positive and negative terminals of power supplies are connected properly. Otherwise, the current or power consumption may exceed the absolute maximum rating, and exceeding the rating(s) may cause breakdown, damage or deterioration of the device, which may result in injury by explosion or combustion. In addition, do not use any device that has had current applied to it while inserted incorrectly or in the wrong orientation even once.

(5) Carefully select power amp, regulator, or other external components (such as inputs and negative feedback capacitors) and load components (such as speakers).

If there is a large amount of leakage current such as input or negative feedback capacitors, the IC output DC voltage will increase. If this output voltage is connected to a speaker with low input withstand voltage, overcurrent or IC failure can cause smoke or ignition. (The over current can cause smoke or ignition from the IC itself.) In particular, please pay attention when using a Bridge Tied Load (BTL) connection type IC that inputs output DC voltage to a speaker directly.

Points to remember on handling of ICs

(1) Heat Dissipation Design

In using an IC with large current flow such as a power amp, regulator or driver, please design the device so that heat is appropriately dissipated, not to exceed the specified junction temperature (Tj) at any time or under any condition. These ICs generate heat even during normal use. An inadequate IC heat dissipation design can lead to decrease in IC life, deterioration of IC characteristics or IC breakdown. In addition, please design the device taking into consideration the effect of IC heat dissipation on peripheral components..

(2) Back-EMF

When a motor rotates in the reverse direction, stops, or slows down abruptly, a current flow back to the motor's power supply due to the effect of back-EMF. If the current sink capability of the power supply is small, the device's motor power supply and output pins might be exposed to conditions beyond maximum ratings. To avoid this problem, take the effect of back-EMF into consideration in your system design.

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About solderability, following conditions were confirmed

- Solderability
 - (1) Use of Sn-37Pb solder Bath
 - · solder bath temperature = 230°C
 - dipping time = 5 seconds
 - the number of times = once
 - · use of R-type flux
 - (2) Use of Sn-3.0Ag-0.5Cu solder Bath
 - · solder bath temperature = 245°C
 - · dipping time = 5 seconds
 - the number of times = once
 - · use of R-type flux

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OOO «ЛайфЭлектроникс" "LifeElectronics" LLC

ИНН 7805602321 КПП 780501001 P/C 40702810122510004610 ФАКБ "АБСОЛЮТ БАНК" (ЗАО) в г.Санкт-Петербурге К/С 3010181090000000703 БИК 044030703

Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибьюторов Европы, Америки и Азии.

С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибьюторских договоров

Мы предлагаем:

- Конкурентоспособные цены и скидки постоянным клиентам.
- Специальные условия для постоянных клиентов.
- Подбор аналогов.
- Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.
- Приемлемые сроки поставки, возможна ускоренная поставка.
- Доставку товара в любую точку России и стран СНГ.
- Комплексную поставку.
- Работу по проектам и поставку образцов.
- Формирование склада под заказчика.
- Сертификаты соответствия на поставляемую продукцию (по желанию клиента).
- Тестирование поставляемой продукции.
- Поставку компонентов, требующих военную и космическую приемку.
- Входной контроль качества.
- Наличие сертификата ISO.

В составе нашей компании организован Конструкторский отдел, призванный помогать разработчикам, и инженерам.

Конструкторский отдел помогает осуществить:

- Регистрацию проекта у производителя компонентов.
- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



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